

AMENDMENTS TO THE SPECIFICATION

Please amend the Specification as follows:

Page 2, paragraph [0002]

[0002] In wafer bump electroplating technology, a substrate such as wafer is placed on a cathode, and metal ions from anode and plating solution are attached on the wafer to form a metal bump. A conventional electroplating method is disclosed in U.S. patent ~~6152167~~ 6,156,167. A wafer is placed on a seal, and a base of a compress and position apparatus is directly pressed on the rim of the wafer so that the seal under the wafer is deformed to prevent the plating solution from polluting the region in the back of the wafer.

Page 6, paragraph [0029]

[0029] Referring to Figs. 2 and 3, a plane 234 is defined on the lateral surface of the housing 206. The housing 206 is disposed on the first plane 226 of the base 204 and connected to the first plane 226. The housing 206 has a central opening 236 on the top thereof, a first vent 238 and a second vent 240. The first and second vents 238, 240 are connected to a gas supply device by a pipeline. Similarly, the opening 236 has a groove 238 on the periphery thereof receiving an elastic element 270 made of rubber such as an O-ring. The elastic element 270 abuts the inner wall of the guiding column to avoid gas leakage. The housing 206 also has a first aperture 244 connected to the first vent 238 and a second aperture 246 connected to the second vent 240. In addition, the guiding column 202 and the cylinder 214 are disposed in the housing 206. The first end 218 of the guiding column 202 passes through the central opening 236 of the ~~hosinhousing~~ 206. The first plane 226 of the base 204 is connected to the housing 206.

Page 7, paragraph [0034]

[0034] Fig. 5 is a schematic view of the pressing of the invention showing the locating pin escaping from the locating hole. Referring to Fig. 3 and 5, when gas is provided through the second aperture 246, the housing 206 is lowered down. As the annular portion 210 is disposed on the first plane 226 of the base 212, the annular portion 210 and the pressing plate 212 is pushed downward by the housing 206. When the pressing plate 212 of the embodiment contacts the substrate 260, only a part of the weight of the pressing plate 212 is sustained by the substrate 260 due to the distance H between the base 204 and the convex portion 232. The distance H provides an appropriate space for the locating pin 230 escaping from the locating hole 248. The housing 206 moves downward until the locating pin 230 escaping from the locating hole 248 and the convex portion 232 contacting the pressing plate 212.